

In re Patent Application of:
ZIARI et al
Serial No. 10/016,473
Filed: December 10, 2001

IN THE DESCRIPTION

Please replace paragraph [0033] with the following amended paragraph:

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[0033] The fiber bonding pad 50 provides a robust attachment point to the fiber mount and a solder barrier. The fiber bonding pad 50 also should allow lateral heat conduction through the thickness of the layer(s) provided by the fiber bonding pad 50. As can be appreciated, there are many variations that may be readily apparent to those skilled in the art, including removal of one or more of the layers, the addition of other layers, and/or substitution of layers with similar properties. Fig. 4 illustrates a plan view the fiber bonding pad 50. Fig. 5 illustrates a cross-sectional view of the solder 52 and the fiber bonding pad 50. For simplicity, the top portion of the fiber bonding pad 50, including layers 60a, 60b, 60c, and 60d, is labeled as 60, while the lower portion of the fiber bonding pad 50, including layers 60e, 60f, 60g, and 60h, is labeled as 62.